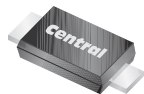


Material Composition Specification

SOD-323FL Case



Device average mass **5.0 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.2%	0.06	Si	7440-21-3	1.2%	0.06	12,000
bond wire	copper	0.2%	0.01	Cu	7440-50-8	0.2%	0.01	2,000
leadframe	Cu alloy	48%	2.4	Cu	7440-50-8	47.92%	2.396	479,200
				Fe	7439-89-6	0.08%	0.004	800
encapsulation*	EMC GREEN	50.28%	2.514	silica	60676-86-0	38.8%	1.94	388,000
				epoxy resin	29690-82-2	5.0%	0.25	50,000
				phenol resin	9003-35-4	4.8%	0.24	48,000
				carbon black	1333-86-4	0.16%	0.008	1,600
				metal hydroxide	1309-42-8	1.52%	0.076	15,200
plating	matte tin	0.32%	0.016	Sn	7440-31-5	0.32%	0.016	3,200

*EMC GREEN molding compound is Halogen Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (11-January 2012)